Special Issue

Bioinspired 3D Printing in 2021

Message from the Guest Editor

Additive manufacturing (three-dimensional (3D) printing) has created new opportunities for manipulating and mimicking the intrinsically multiscale, multimaterial, and multifunctional structures in nature. Understanding natural structures and replicating them by 3D printing for various engineering applications will lead us to drive the biomimicry field forward. Meanwhile, the fabrication challenges presented by biomimicry will lead to more novel biomimetic 3D printing processes. This Special Issue will focus on research advances in the areas of bioinspired 3D printing for future engineering systems. The growth of bioinspired 3D printing technology will open intriguing perspectives for developing bioinspired materials and structures on the basis of novel 3D printing processes together with new computer-aided design and simulation methods.

Guest Editor

Dr. Yang Yang
Department of Mechanical Engineering, San Diego State University,
San Diego, CA 92182, USA

Deadline for manuscript submissions

closed (30 November 2021)

Micromachines

an Open Access Journal by MDPI

Impact Factor 3.0
CiteScore 6.0
Indexed in PubMed

mdpi.com/si/73303

Micromachines
Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland
Tel: +41 61 683 77 34
micromachines@mdpi.com

mdpi.com/journal/micromachines

Micromachines

an Open Access Journal
by MDPI

Impact Factor 3.0
CiteScore 6.0
Indexed in PubMed

mdpi.com/journal/micromachines

MDPI

About the Journal

Message from the Editor-in-Chief

You are invited to contribute research articles or comprehensive reviews for consideration and publication in *Micromachines* (ISSN 2072-666X). *Micromachines* is published in the open access format. Research articles, reviews and other contents are released on the internet immediately after acceptance. The scientific community and the general public have unlimited free access to the content as soon as it is published. As an open access journal, *Micromachines* is supported by the authors or their institutes by payment of article processing charges (APC) for accepted papers. We are pleased to welcome you as our authors.

Editor-in-Chief

Prof. Dr. Ai-Qun Liu
1. Department of Electrical and Electronic Engineering, The Hong Kong Polytechnic University, Hong Kong, China
2. School of Electrical and Electronic Engineering, Nanyang Technological University, Singapore 639798, Singapore

Author Benefits

High Visibility:

indexed within Scopus, SCIE (Web of Science), PubMed, PMC, Ei Compendex, dblp, and other databases.

Journal Rank:

JCR - Q2 (Instruments and Instrumentation) / CiteScore - Q1 (Mechanical Engineering)

Rapid Publication:

manuscripts are peer-reviewed and a first decision is provided to authors approximately 17.2 days after submission; acceptance to publication is undertaken in 1.9 days (median values for papers published in this journal in the first half of 2025).